

IN THE CLAIMS

Please amend the claims as follows:

Please cancel claims 17, 18, and 36 without prejudice.

Claims 1-20. (Canceled)

21. (Previously Presented) An electronic package comprising:
a package substrate including
 a thin, flexible, electrically insulating film including a conductor region to mount
an integrated circuit;
 a plurality of traces, at least some of which are within the conductor region;
 one or more vias within the film and coupled to corresponding ones of the traces;
and
 a plurality of lands on a surface of the film and coupled to the traces, the plurality
of lands including a plurality of signal lands around the periphery of the conductor
region, the plurality of lands further including a plurality of power and ground lands
within a central core region of the conductor region; and
an integrated circuit including a plurality of pads coupled to the plurality of lands in a ball
grid array.
22. (Previously Presented) The electronic package recited in claim 21, wherein the film is
formed of material selected from the group consisting of a polymeric film, polyimide, polyester,
polyparabanic acid, epoxy, and fiberglass.
23. (Previously Presented) The electronic package recited in claim 21, wherein the film
comprises a plurality of layers, each of the layers comprising a plurality of traces in the
conductor region, and wherein each layer has a thickness within the range of approximately .15
to .30 millimeters.

24-25. (Canceled)

26. (Previously Presented) An electronic system including at least one electronic assembly comprising:

a thin, flexible, electrically insulating film including a conductor region, a plurality of traces in the conductor region, and a plurality of lands formed directly upon a surface of the film and coupled to the traces, the plurality of lands including a plurality of signal lands around the periphery of the conductor region, the plurality of lands further including a plurality of power and ground lands within a central core region of the conductor region;

an integrated circuit including a plurality of pads coupled to the plurality of lands in a ball grid array; and

wherein the film comprises a plurality of contiguous layers, selected ones of which comprise a plurality of traces in the conductor region, and wherein the film comprises one or more vias coupled to corresponding ones of the traces.

27. (Previously Presented) The electronic system recited in claim 26, wherein the film is formed of material selected from the group consisting of a polymeric film, polyimide, polyester, polyparabanic acid, epoxy, and fiberglass.

28-30. (Canceled)

31. (Previously Presented) A data processing system comprising:

a bus coupling components in the data processing system;

a display coupled to the bus;

a memory coupled to the bus; and

a processor coupled to the bus and comprising an electronic assembly including,

a thin, flexible, electrically insulating film including a conductor region, a plurality of traces in the conductor region, one or more vias coupled to corresponding ones of the traces, and a plurality of lands formed directly upon a surface of the film and

coupled to the traces, the plurality of lands including a plurality of signal lands around the periphery of the conductor region, the plurality of lands further including a plurality of power and ground lands within a central core region of the conductor region; and
an integrated circuit including a plurality of pads coupled to the plurality of lands in a ball grid array.

32. (Previously Presented) The data processing system recited in claim 31, wherein the film is formed of material selected from the group consisting of a polymeric film, polyimide, polyester, polyparabanic acid, epoxy, and fiberglass.

33. (Previously Presented) The data processing system recited in claim 31, wherein the film comprises a plurality of layers, each of the layers comprising a plurality of traces in the conductor region.

Claims 34-36. (Canceled)

37. (Previously Presented) A package substrate comprising:
a thin, flexible, electrically insulating film including a conductor region to mount an integrated circuit;
a plurality of traces, at least some of which are within the conductor region;
one or more vias within the film and coupled to corresponding ones of the traces; and
a plurality of lands on a surface of the film and coupled to the traces, wherein the lands are to mount corresponding pads of the integrated circuit, the plurality of lands including a plurality of signal lands around the periphery of the conductor region, the plurality of lands further including a plurality of power and ground lands within a central core region of the conductor region.

38. (Previously Presented) The package substrate recited in claim 37, wherein the film is formed of material selected from the group consisting of a polymeric film, polyimide, polyester, polyparabanic acid, epoxy, and fiberglass.

39. (Previously Presented) The package substrate recited in claim 37, wherein the film comprises a plurality of layers, each of the layers comprising a plurality of traces.

40. (Previously Presented) The package substrate recited in claim 39, wherein the one or more vias couple traces within selected layers.

41. (Canceled)

42. (Previously Presented) The electronic package recited in claim 21, wherein the film comprises a plurality of contiguous layers, selected ones of which layers comprise selected ones of the plurality of traces, and wherein selected ones of the one or more vias couple traces within selected layers.

43. (Canceled)

44. (Previously Presented) The electronic system recited in claim 26, wherein the one or more vias couple traces within selected layers.

45. (Canceled)

46. (Previously Presented) The data processing system recited in claim 33, wherein the one or more vias couple traces within selected layers.